

Datasheet DS 60S 220532(B.1)

Radiation-Tolerant Quad-Core ARM® Cortex®-A72 1.8GHz Microprocessor

1 Introduction

LS1046-Space is a Space Radiation-Tolerant Microprocessor.

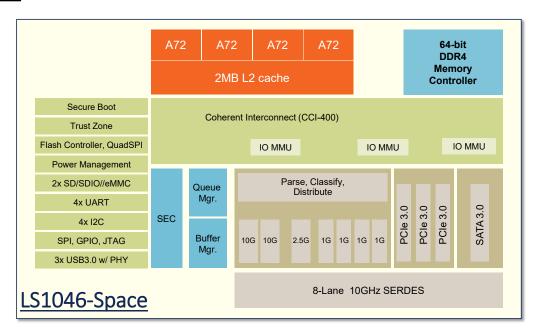
It embeds a Quad-Core ARM® Cortex®-A72 Microprocessor running up to 1.8GHz and bringing 30k DMIPS computing capabilities, with ECC-protected L1 and L2 cache memories for reliable behavior. It features a rich set of peripherals, including integrated packet processing acceleration, high speed serial links supporting 10 Gb Ethernet, PCle® Gen3, SATA 3.0 and USB, as well as a number of general purpose interfaces such as SPI, I²C, and UART.

It is a Space-qualified, radiation-tolerant version of Teledyne e2v LS1046 standard Hi-Rel component. This document provides the specific features and characteristics of the LS1046-Space. From the functional and computing performance point of view, LS1046-Space is equivalent to the standard version. For the general characteristics, the datasheet and reference manual of the commercial version are applicable.

2 Typical end applications

- Communication Satellites / Constellations Requiring AI / Security
- Observation Satellites AI / Security / Automated situation detection & awareness
- High bandwidth Space Observation
- Defense In Space
- Meteorological Satellites
- Data Storage / Servers in the Sky
- Human Mission Exploration & Science Missions

3 Block Diagram



4 Space-Grade Parts Key Features

4.1 Space Qualification

- Up to NASA Level 1 (based on NASA EEE-INST-002 Section M4 PEMs)
- Up to Class 1 (ECSS-Q-ST-60-13C)
- · Full lot traceability and serializing

4.2 Radiation Tolerance

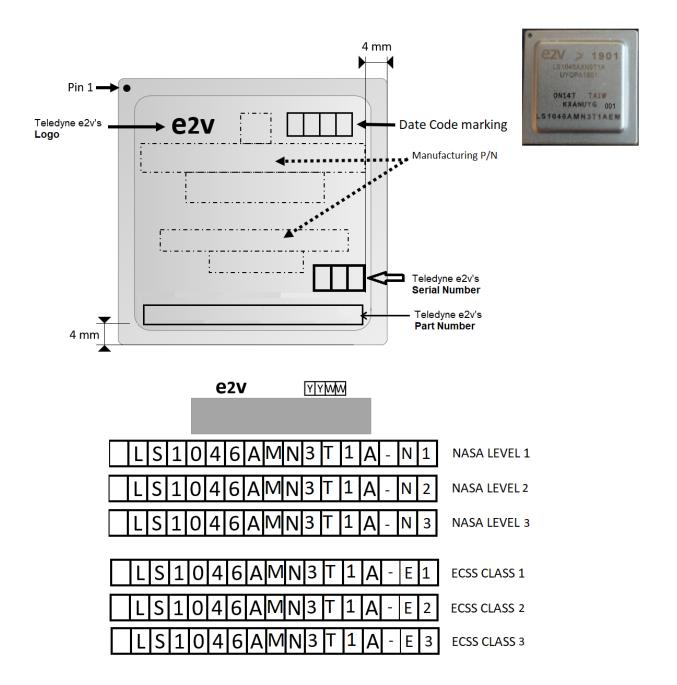
Key figures of the radiation performance of the device are highlighted below:

- SEL LET Threshold > 62.5 MeV.cm²/mg
- SEU LET Threshold 1.8 MeV.cm²/mg Upset cross-section @ 62.5 MeV.cm²/mg = 3.25 E-9 cm²/bit
- SEFI LET Threshold 1.8 MeV.cm²/mg
 SEFI cross-section @ 62.5 MeV.cm²/mg = 7.23 E-5 cm²/device
- TID 100 krad

Complete radiation reports available for SEE (heavy-ions and protons) and TID testing.

4.3 Package and physical properties

Marking drawing for the LS1046-Space is given below:



Physical properties

- Solder Balls Composition 63% Sn, 37% Pb
- Mass of the device is 4.06g
- CTE of the package: please contact your Teledyne e2v technical support
- Low outgassing: Compliant with ASTM 595 and ESCC-Q-ST-70-02

General package characteristics are given in the datasheet of the standard version (Datasheet DS1202).

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5 <u>LS1046-Space ordering information</u>

LS	n	nn	n	Х	t	е	n	С	t	r	Quality Level
Generation	Performance Level	Number of Virtual cores	Unique ID	Core Type	Temperature Range	Encryption	Package Type	CPU Speed	DDR Data Rate	Die Revision	Grade ⁽¹⁾
LS = Layer	1	04 = four	6	A =	M = Military	E =	3 =	P =	1 =	A =	-N1 = Nasa Level 1
scape		cores		Arm	-55°C − 125°C	Encryption	FCPBGA	1400	2100	Rev 1.0	-N2 = Nasa Level 2
							C4 Pb-	MHz	MHz		-N3 = Nasa Level 3
		02 = two				N = Non-	free/C5				EM = Engineering Models
		cores				Encryption	Leaded	Q =			EQM = Engineering
								1600			Qualification Models
								MHz			-E1 = ECSS Class 1
											-E2 = ECSS Class 2
								T =			-E3 = ECSS Class 3
								1800			
								MHz			

⁽¹⁾ To know more about grades please refer to NE60S220869 in our web page

6 LS1046 Product Features

Please refer to Teledyne e2v datasheet reference: <u>Datasheet DS1202</u>

7 Revision history

This table summarizes revisions to this document.

Issue	Date	Comments		
Α	March 2021	Initial revision		
A.1	October 2021	Add outgassing information		
В	January 2022	EQM Engineering Qualification Model/ ref model NE60S220869		

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